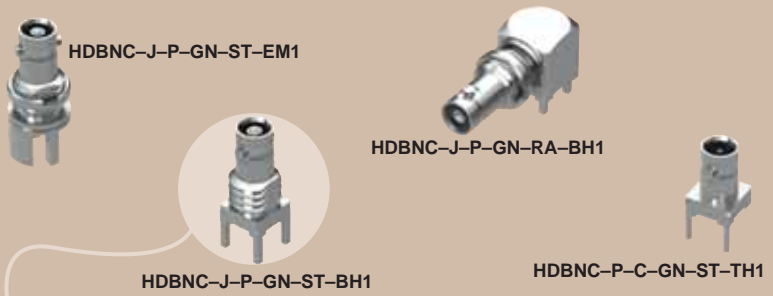




HDBNC SERIES



75Ω HIGH DENSITY BNC JACKS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HDBNC-TH, www.samtec.com?HDBNC-BH1 or www.samtec.com?HDBNC-EM

- Shell Material:** Au plated Brass
- Contact Material:** Copper Alloy
- Insulator Material:** PTFE
- Impedance:** 75Ω ±2Ω
- Frequency Range:** 0~6 GHz
- V.S.W.R.:** 1.45 max (with optimized launch design)
- Working Voltage:** 330 Vrms max
- Dielectric Withstanding:** 1500 Vrms min
- Contact Resistance:** Center Contact: 1,5mΩ max
Outer Contact: 0,4mΩ max
- Operating Temperature:** -65°C to +125°C
- RoHS Compliant:** Yes
- Lead-Free Solderable:** Yes

Mates with: RFB6T, RFB8T, RFA6T



Patented design and bayonet latch

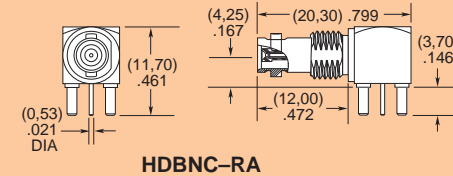
20% reduction in weight of traditional BNCs

Extended performance of 6 GHz for high density

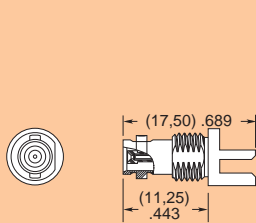
EXTRACTION TOOL

- Hand tool for quickly installing/uninstalling
- Contact Samtec.

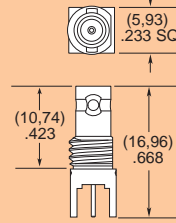
HDBNC	GENDER	TYPE	PLATING	ORIENTATION	TERMINATION
-J	= Jack	-P = PCB Mount	-GN = 10μ" (0,25 μm) Gold contact, 100μ" (2,54 μm) Nickel shell	-ST = Straight -RA = Right Angle	-BH1 = Through-hole (1,60 mm) .062 Board -BH2 = Through-hole (2,36 mm) .093 Board (-RA only) -EM1 = Edge Mount (-ST only) -TH1 = Through-hole (-ST only)



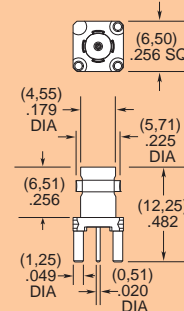
HDBNC-RA



HDBNC-EM1



HDBNC-BH1



HDBNC-TH1

Note: Compatible with Amphenol's HD-BNC™

* Designed to meet SMPTE 424M 3G SDI specification.

Due to technical progress, all designs, specifications and components are subject to change without notice.